EPCOS

Microwave Ceramics and Modules **Filter**

Filter for WLAN [5470-5725] MHz B69842N5597A255

Preliminary data

Features

- SMD filter consisting of coupled resonators with stepped impedances
- $MgTiO_3$-$CaTiO_3$ ($\varepsilon_r = 21$ / $TC_f = 0 \pm 10$ ppm/K) with a coating of copper (10µm) and tin (>5µm)
- Excellent reflow solderability, no migration effect due to copper/tin metallization

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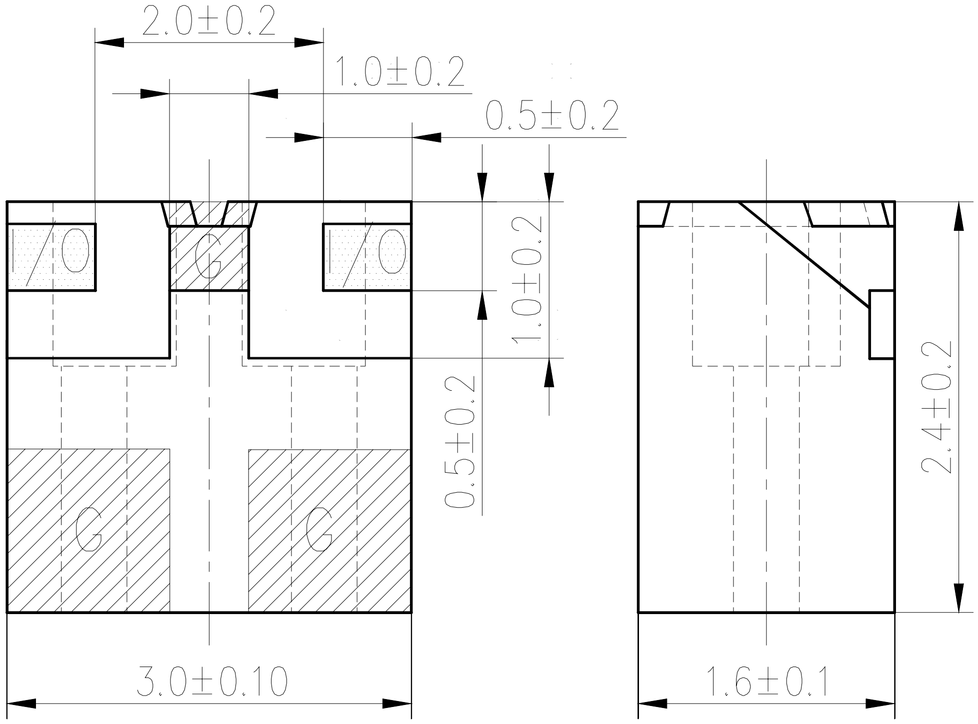
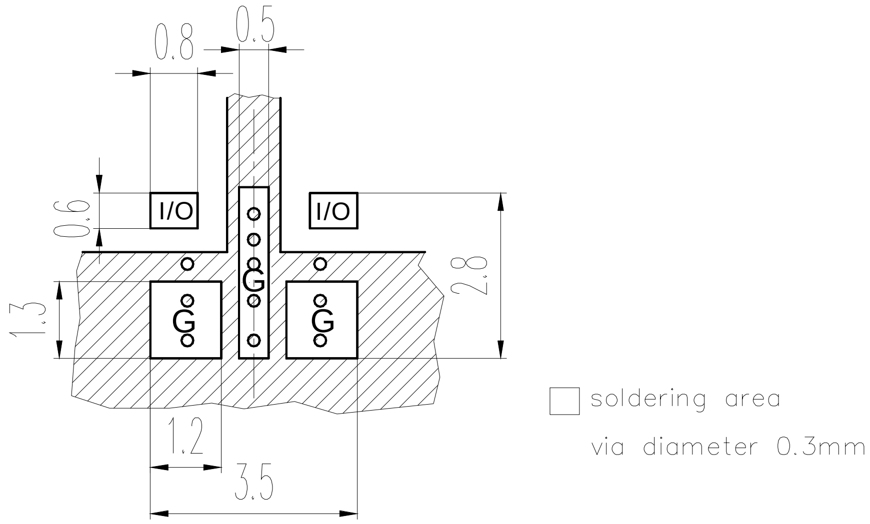
Component drawing



S2H11_010601.DWG→WMF

Recommended footprint



FOOTPR_240502.DWG→WMF

Filter for WLAN [5470-5725] MHz B69842N5597A255

Preliminary data

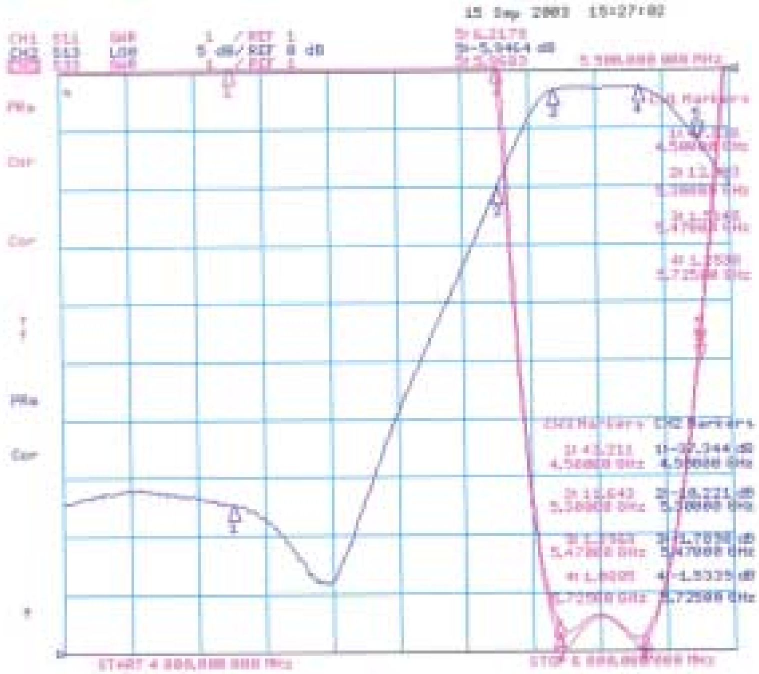
Characteristics

		min.	typ.	max.	
Center frequency	f_C	-	5597.5	-	MHz
Insertion loss	α_{IL}		1.3	1.6	dB
Passband	B	255			MHz
Amplitude ripple (peak - peak)	$\Delta\alpha$				dB
Standing wave ratio	SWR		1.5	2.0	
Impedance	Z		50		Ω
Power	P			1.0	W
Attenuation	α				
at DC to 4500 MHz		35	40		dB
at 5300 MHz		8			dB
at 5900 MHz		5			dB

Maximum ratings

IEC climatic category (IEC 68-1)		- 40/+ 90/56	
Operating temperature	T_{op}	-40 / + 85	°C

Typical passband characteristic



Processing information

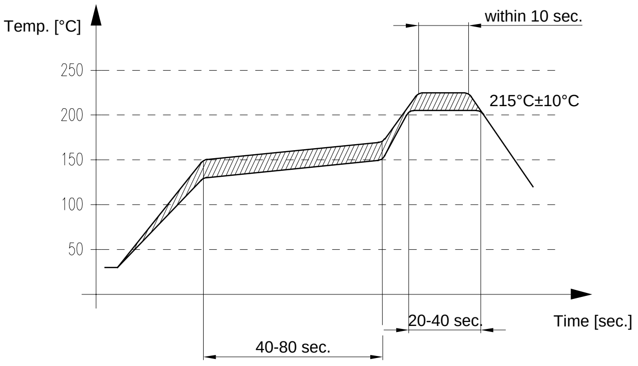
ZNr.: 577 (FILT95_2)

- Wettability to IEC 68-2-58: ≥ 75% (after aging)

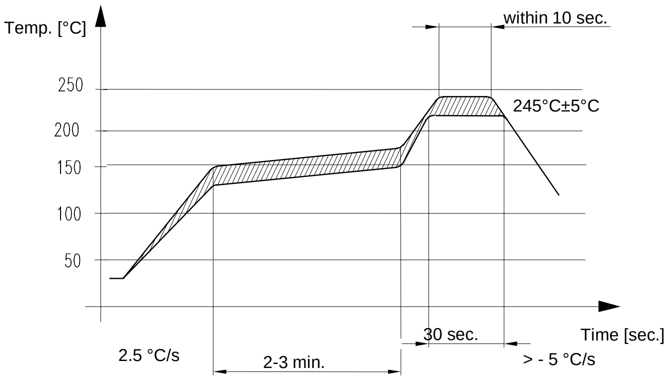
Soldering requirements

	Profile for eutectic SnPb solder paste	Profile for leadfree solder paste	
Soldering type	reflow	reflow	
Maximum soldering temperature (measuring point on top surface of the component)	235 (max. 2 sec.) 225 (max. 10 sec.)	260 (max. 2 sec.) 250 (max. 10 sec.)	°C °C

Recommended soldering conditions (infrared):



eutectic SnPb solder paste profile



leadfree solder paste profile

Delivery mode

- Blister tape acc. to IEC 286-3, PS, grey
- Pieces/tape: 4000

t.b.d.